ON Semiconductor®

Initial Product/Process Change Notification

Document #:IPCN23837Z
Issue Date:26 Feb 2021

Title of Change:	Wafer fab transfer to ON Semiconductor Gresham, Oregon USA from ON Semiconductor Fab2, Oudenaarde, Belgium related to Fab2 sale
Proposed Changed Material First Ship Date:	28 Jul 2022 or earlier if approved by customer
Current Material Last Order Date:	Jun 30, 2021 with flexibility for update at FPCN issue date
Current Material Last Delivery Date:	12months after FPCN issue date, unless otherwise mutually agreed
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local ON Semiconductor Sales Office or Alicia.Tuckett@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Catherine.DeKeukeleire@onsemi.com
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 12 months prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.

Change Category

Category	**Type of Change**
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter

Description and Purpose:

Wafer fab transfer to ON Semiconductor Gresham, Oregon USA from ON Semiconductor Fab2, Oudenaarde, Belguim due to Fab2 sale.

	From	To
Wafer fab location	Fab2, Oudenaarde, Belgium (Current Fab)	ON Semiconductor Gresham, Oregon, USA (New Fab)
Wafer Diameter	Substrate: Si (150mm) 6”	Substrate: Si (200mm) 8"
Passivation layer	Current: no polyimide	New: polyimide (Gresham)
Product marking change	Documented at product level at FPCN issue	
Package BOM changes	Bonding wire material change (Au -> Cu)	

Reason / Motivation for Change:	Source/Supply/Capacity Changes Process/Materials Change
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification and qualification plan. No anticipated impacts.

Sites Affected:	
ON Semiconductor Sites	**External Foundry/Subcon Sites**
ON Semiconductor Gresham, Oregon USA	None
ON Semiconductor Fab2, Oudenaarde, Belgium	

Marking of Parts/ Traceability of Change:	Traceability guaranteed by datecode, specific line one marking and Rev ID register

Reliability Data Summary:

Qualification plan is device specific and will be provided upon request.

Electrical Characteristics Summary:

Electrical characteristics will be provided by Jun, 2021.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Current Part Number	New Part Number	Qualification Vehicle
NCV7707DQR2G	NCV7707DQCR2G	NA
NCV7707DQBR2G	NCV7707DQCR2G	NA
NCV7710DQR2G	NCV7710DQBR2G	NA
SCV7710DQR2G	NCV7710DQBR2G	NA